Solder Paste "for High-Speed Printing"

Bringing stable performance for high-speed circuit board printing. Increased productive higher efficiency and cost reductions throughout the entire manufacturing process.

M-HP-S

Sn-Ag-Cu solders

- 1. Solid high-speed circuit board printing with a maximum squeegee speed of 150mm/sec, leading to
- 2. Cleaning has been made easier with a metal stencil that is less prone to clogging and smearing.
- 3. Increased tact-up for better balancing with the mounter, resulting in reduced labor all round.
- 4. The unit has the same high flux reliability and durability of existing paste (TM-HP).

Examples of application: High-speed circuit board printing, easier cleaning.



Comparison of printability with different squeegee speeds (using degraded paste)

[Print conditions] - Printing machine used: HI GARD HG-600 (made by Hitachi Industries Co. Ltd. Company) - Squeegee speed: 25, 150mm/sec - Separation speed: 1.8mm/sec - Squeegee material: made of Urethane (hardness 80°) - Print pressure: 1.4N

[Degradation condition] - 10rpm, 32h - Machine used: Viscous mixing machine (25°C, humidity 85%) made by Makom Co., Ltd.

Normal Printing (25mm/sec.)



0.40mm Slit

0.28mm Dot

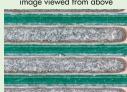






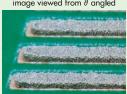


High-speed Printing (150mm/sec)









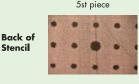
Check of Clogging on back of Stencil and Print Condition after Continuous Printing

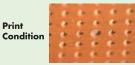
[Condition] Continuous printing of 0.3mm dots without cleaning. Perform check of clogging on back of stencil and print condition after printing 5, 50, and 100 pieces. -Squeegee Speed: 100mm/sec. -Printing Pressure: 35x10°N. -Squeegee Material: Metal squeegee. -Snap off Speed: 10mm/sec (Constant speed). -dearance: -0.5mm. -Stencil thickness: 120µm











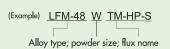








Product name component for solder paste



Solder paste products specification

Flux name	Alloy type	Powder size	Flux content	Viscosity	Melting point temperature
TM-HP-S	LFM-48 (Sn-3.0Ag-0.5Cu)	x, w	12.0%	170Pa · s	217-220°C

^{*}LFM-48 has been sublicensed for JP PAT No. 3027441 and US PAT No. 5527628. *The standard container contains 500g. *Powder sizes are X: 25~45µm, W: 20~38µm. *When your ordered product is out of stock, please contact our sales representative

